

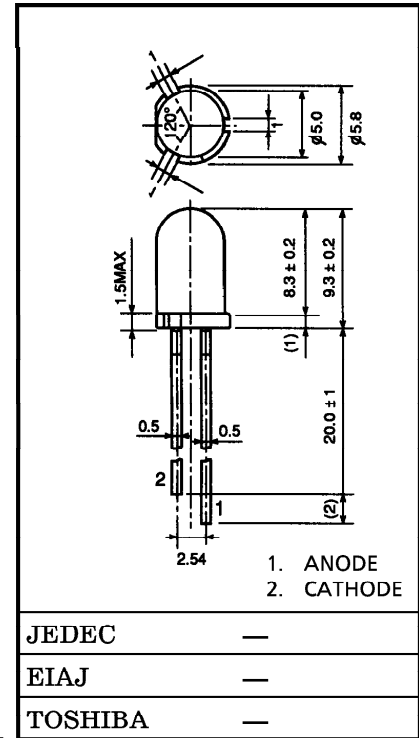
TOSHIBA LED LAMP InGaAlP ORANGE LIGHT EMISSION

# TLOH157P

PANEL CIRCUIT INDICATOR

Unit in mm

- 5mm DIAMETER (T1-3 / 4)
- InGaAlP ORANGE LED
- All Plastic Mold Type.
- Colorless Clear Lens
- Low Drive Current, High Intensity Orange Light Emission  
Recommended Forward Current :  $I_F = 1 \sim 20\text{mA}$  (DC)
- All Plastic Molded Lens, Provides an Excellent ON-OFF Contrast Ratio.
- Fast Response Time, Capable of Pulse Operation.
- High Power Luminous Intensity
- Without stand-offs
- APPLICATIONS : Suitable for Outdoor Message Signboard, Safety equipment, automotive use.



Weight : 0.31g

MAXIMUM RATINGS (Ta = 25°C)

| CHARACTERISTIC              | SYMBOL    | RATING  | UNIT |
|-----------------------------|-----------|---------|------|
| Forward Current (DC)        | $I_F$     | 50      | mA   |
| Reverse Voltage             | $V_R$     | 4       | V    |
| Power Dissipation           | $P_D$     | 125     | mW   |
| Operating Temperature Range | $T_{opr}$ | -30~85  | °C   |
| Storage Temperature Range   | $T_{stg}$ | -40~120 | °C   |

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● Gallium arsenide (GaAs) is a substance used in the products described in this document. GaAs dust and fumes are toxic. Do not break, cut or pulverize the product, or use chemicals to dissolve them. When disposing of the products, follow the appropriate regulations. Do not dispose of the products with other industrial waste or with domestic garbage.

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ELECTRO-OPTICAL CHARACTERISTICS (Ta = 25°C)

| CHARACTERISTIC           | SYMBOL          | TEST CONDITION             | MIN. | TYP. | MAX. | UNIT          |
|--------------------------|-----------------|----------------------------|------|------|------|---------------|
| Forward Voltage          | $V_F$           | $I_F = 20\text{mA}$        | —    | 2.1  | 2.5  | V             |
| Reverse Current          | $I_R$           | $V_R = 4\text{V}$          | —    | —    | 50   | $\mu\text{A}$ |
| Luminous Intensity       | TLOH157P        | $I_F = 20\text{mA}$ (Note) | 850  | 2000 | —    | mcd           |
|                          | TLOH157P (ST)   |                            | 850  | —    | 4140 |               |
|                          | TLOH157P (TU)   |                            | 1530 | —    | 7360 |               |
| Peak Emission Wavelength | $\lambda_p$     | $I_F = 20\text{mA}$        | —    | 612  | —    | nm            |
| Spectral Line Half Width | $\Delta\lambda$ | $I_F = 20\text{mA}$        | —    | 15   | —    | nm            |
| Dominant Wavelength      | $\lambda_d$     | $I_F = 20\text{mA}$        | —    | 605  | —    | nm            |

(Note) Rank selection carried out under next range respectively, although it needs  $\pm 15\%$  additional for guaranteed limits.

S : 1000-2000mcd, T : 1800-3600mcd, U : 3200-6400mcd

PRECAUTION

Please be careful of the followings

- Soldering temperature : 260°C MAX. Soldering time : 3s MAX.  
(Soldering portion of lead : up to 2mm from the body of the device)
- If the lead is formed, the lead should be formed up to 5mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.

